

## Features

- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automated Insertion
- High Conductance
- High Reverse Breakdown Voltage Rating
- **Lead, Halogen and Antimony Free, RoHS Compliant**
- **"Green" Device (Notes 3 and 4)**
- **Qualified to AEC-Q101 Standards for High Reliability**

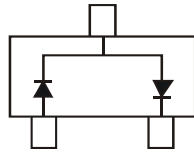
## Mechanical Data

- Case: SOT-23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Marking Information: See Diagrams Below and Page 2
- Ordering Information: See Page 2
- Weight: 0.008 grams (approximate)

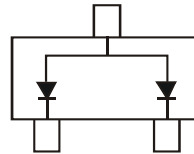
SOT-23



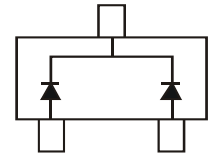
TOP VIEW



MMBD3004S Marking: KAE



MMBD3004A Marking: KAD



MMBD3004C Marking: KAC

## Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	$V_{RRM}$	350	V
Working Peak Reverse Voltage	$V_{RWM}$	300	V
DC Blocking Voltage	$V_R$		
RMS Reverse Voltage	$V_{R(RMS)}$	212	V
Forward Continuous Current (Note 2)	$I_F$	225	mA
Peak Repetitive Forward Current (Note 2)	$I_{FRM}$	625	mA
Non-Repetitive Peak Forward Surge Current		@ $t = 1.0\mu\text{s}$	4.0
		@ $t = 1.0\text{s}$	1.0

## Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	$P_D$	350	mW
Thermal Resistance Junction to Ambient Air (Note 2)	$R_{\theta JA}$	357	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-65 to +150	$^\circ\text{C}$

## Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 1)	$V_{(BR)R}$	350	—	—	V	$I_R = 150\mu\text{A}$
Forward Voltage	$V_F$	—	0.78	0.87	V	$I_F = 20\text{mA}$
			0.93	1.0		$I_F = 100\text{mA}$
			1.03	1.25		$I_F = 200\text{mA}$
Reverse Current (Note 1)	$I_R$	—	30	100	nA	$V_R = 240\text{V}$
			35	100	$\mu\text{A}$	$V_R = 240\text{V}, T_J = 150^\circ\text{C}$
Total Capacitance	$C_T$	—	1.0	5.0	pF	$V_R = 0\text{V}, f = 1.0\text{MHz}$
Reverse Recovery Time	$t_{rr}$	—	—	50	ns	$I_F = I_R = 30\text{mA}$ , $I_{rr} = 3.0\text{mA}, R_L = 100\Omega$

- Notes:
1. Short duration pulse test used to minimize self-heating effect.
  2. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  3. No purposefully added lead. Halogen and Antimony Free.
  4. Product manufactured with Data Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or  $\text{Sb}_2\text{O}_3$  Fire Retardants.

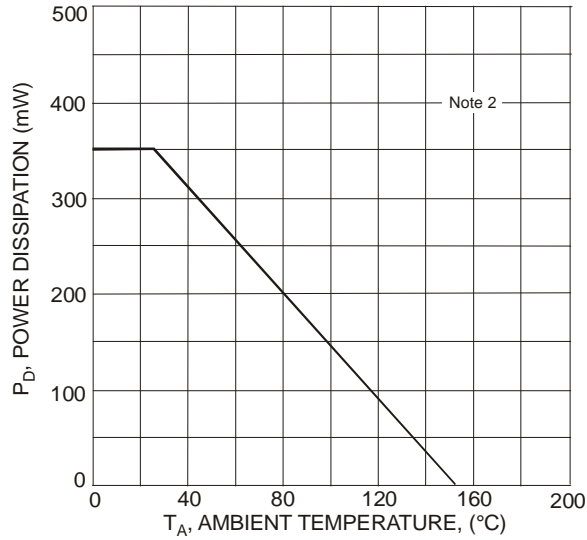


Fig. 1 Power Derating Curve, Total Package

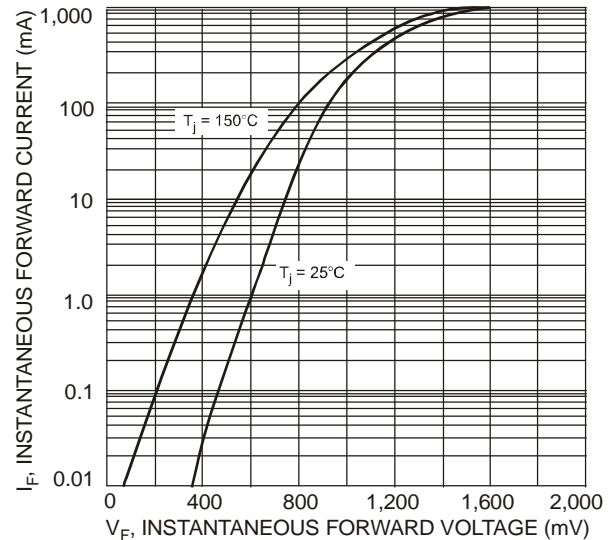


Fig. 2 Typical Forward Characteristics, Per Element

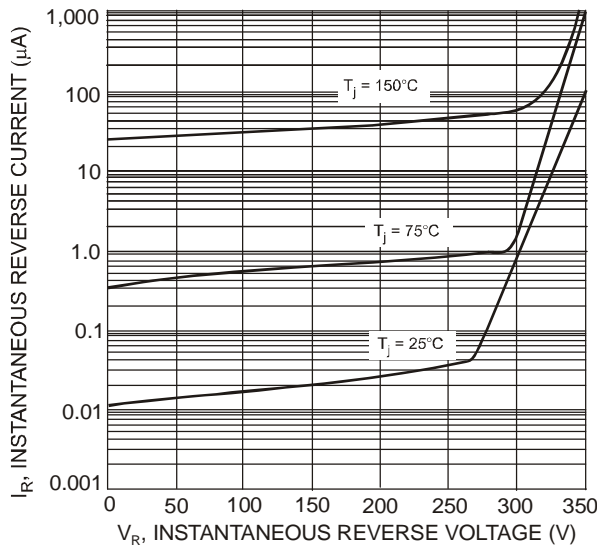


Fig. 3 Typical Reverse Characteristics, Per Element

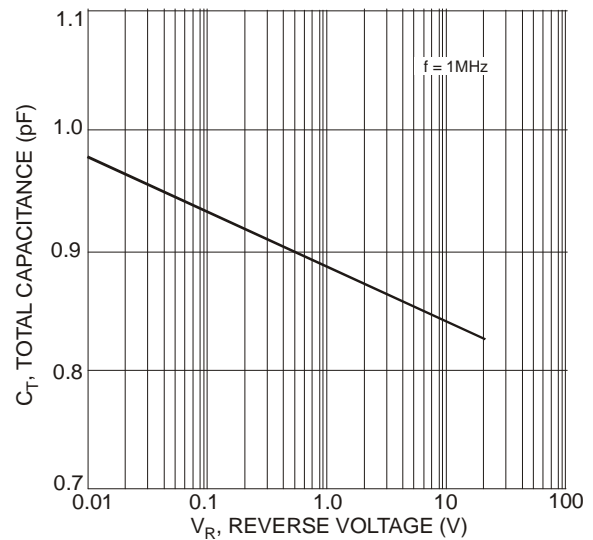


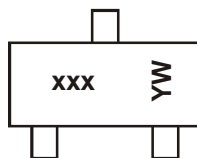
Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

## Ordering Information (Note 5)

Part Number	Case	Packaging
MMBD3004S-7-F	SOT-23	3000/Tape & Reel
MMBD3004S-13-F	SOT-23	10,000/Tape & Reel
MMBD3004A-7-F	SOT-23	3000/Tape & Reel
MMBD3004C-7-F	SOT-23	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

## Marking Information



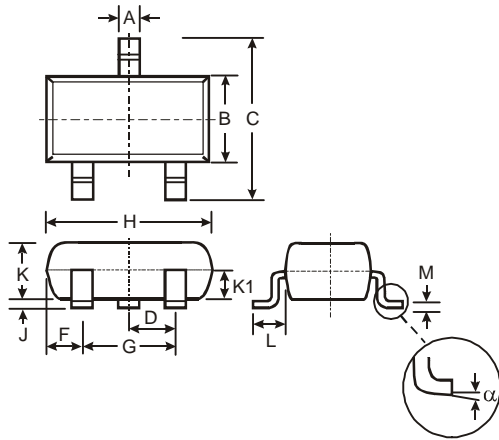
xxx = Product Type Marking Code, See Page 1 Diagrams  
 YW = Date Code Marking  
 Y = Year (ex: T = 2006)  
 M = Month (ex: 9 = September)

### Date Code Key

Year	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	T	U	V	W	X	Y	Z	A	B	C

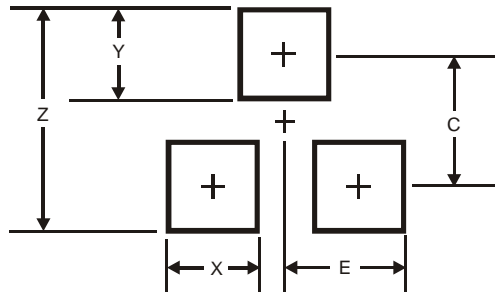
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Package Outline Dimensions**



SOT-23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
α	0°	8°	-
All Dimensions in mm			

**Suggested Pad Layout**



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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